

## **TP65H015G5WS**

#### 650V SuperGaN™ FET in TO-247 (source tab) **Preliminary Datasheet**

#### Description

The TP65H015G5WS 650V, 15 m $\Omega$  gallium nitride GaN FET is a normally-off device using Transphorm's Gen V platform. It combines a state-of-the-art high voltage GaN HEMT with a low voltage silicon MOSFET to offer superior reliability and performance.

The Gen V SuperGaN™ platform uses advanced epi and patented design technologies to simplify manufacturability while improving efficiency over silicon via lower gate charge, output capacitance, crossover loss, and reverse recovery charge.

#### Related Literature

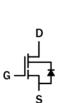
- ANOOO9: Recommended External Circuitry for GaN FETs
- ANOOO3: Printed Circuit Board Layout and Probing
- ANOO10: Paralleling GaN FETs

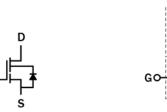
#### **Ordering Information**

Part Number	Package	Package Configuration		
TP65H015G5WS	3 lead T0-247	Source		

#### TP65H015G5WS T0-247 (top view)







**Cascode Schematic Symbol** 

**Cascode Device Structure** 

#### **Features**

- JEDEC qualified GaN technology
- Dynamic R<sub>DS(on)eff</sub> production tested
- · Robust design, defined by
  - Intrinsic lifetime tests
  - Wide gate safety margin
  - Transient over-voltage capability
- Very low Q<sub>RR</sub>
- · Reduced crossover loss

#### **Benefits**

- Enables AC-DC bridgeless totem-pole PFC designs
  - Increased power density
  - Reduced system size and weight
  - Overall lower system cost
- · Achieves increased efficiency in both hard- and softswitched circuits
- Easy to drive with commonly-used gate drivers
- GSD pin layout improves high speed design

#### **Applications**

- Datacom
- Broad industrial
- PV inverter
- Servo motor







Key Specifications		
V <sub>DSS</sub> (V)	650	
V <sub>(TR)DSS</sub> (V)	725	
$R_{DS(on)eff}(m\Omega)\;max^*$	18	
Q <sub>RR</sub> (nC) typ	430	
Q <sub>G</sub> (nC) typ	68	

<sup>\*</sup> Dynamic on-resistance

## **Absolute Maximum Ratings** (T<sub>c</sub>=25 °C unless otherwise stated.)

Symbol	Parameter		Limit Value	Unit
V <sub>DSS</sub>	Drain to source voltage (T <sub>J</sub> = -	55°C to 150°C)	650	
V <sub>(TR)DSS</sub>	Transient drain to source volta	age <sup>a</sup>	725	V
V <sub>GSS</sub>	Gate to source voltage		±20	
P <sub>D</sub>	Maximum power dissipation @	©T <sub>C</sub> =25°C	276	W
I <sub>D</sub>	Continuous drain current @Tc	Continuous drain current @Tc=25°C b		A
ID	Continuous drain current @Tc=100°C b		60	A
I <sub>DM</sub>	Pulsed drain current (pulse wi	Pulsed drain current (pulse width: 10µs)		A
T <sub>C</sub>	Operating temperature	Case	-55 to +150	°C
TJ	Junction		-55 to +150	°C
Ts	Storage temperature		-55 to +150	°C
T <sub>SOLD</sub>	Soldering peak temperature <sup>c</sup>		260	°C

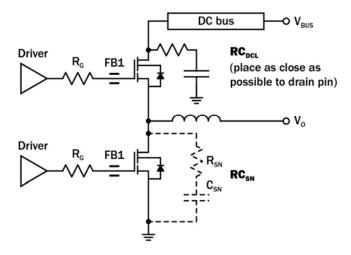
#### Notes:

- a. In off-state, spike duty cycle D<0.01, spike duration <1µs
- o. For increased stability at high current operation, see Circuit Implementation on page 3
- c. For 10 sec., 1.6mm from the case

#### **Thermal Resistance**

Symbol	Parameter	Typical	Unit	
R <sub>OJC</sub>	Junction-to-case	0.45	°C/W	
R <sub>OJA</sub>	Junction-to-ambient	40	°C/W	

### **Circuit Implementation**



Simplified Half-bridge Schematic

Recommended gate drive: (0V, 12V) with R<sub>G</sub>=15 $\Omega$ 

Gate Ferrite Bead (FB1)	Required DC Link RC Snubber (RC <sub>DCL</sub> ) <sup>a</sup>	Recommended Switching Node RC Snubber (RC <sub>SN</sub> ) <sup>b, c</sup>
80-120 Ω at 100MHz	[10nF + 3.3 Ω] x 3	Not necessary

#### Notes:

May 25, 2020

tp65h015G5ws.1

- a.  $RC_{DCL}$  should be placed as close as possible to the drain pin
- 0.  $RC_{SN}$  is needed only if  $R_G$  is smaller than recommendations or operational current exceeds 100C rated  $I_{DMAX}$
- C. If required, please use [10  $\Omega$  + 100pF] x 3 in parallel

### **Electrical Parameters** (T<sub>J</sub>=25 °C unless otherwise stated)

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions	
Forward Device Characteristics							
$V_{(BL)DSS}$	Drain-source voltage	650	_	_	V	V <sub>GS</sub> =0V	
$V_{\text{GS(th)}}$	Gate threshold voltage	3.3	4	4.8	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =2mA	
D	Drain course on registance 3	_	15	18	m.O.	V <sub>GS</sub> =10V, I <sub>D</sub> =60A	
R <sub>DS(on)eff</sub>	Drain-source on-resistance a	_	31	_	- mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =60A, T <sub>J</sub> =150°C	
l	Drain-to-source leakage current	_	7	70		V <sub>DS</sub> =650V, V <sub>GS</sub> =0V	
I <sub>DSS</sub>	Drain-to-source leakage current	_	50	_	μA	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	
	Gate-to-source forward leakage current	_	_	400	n 1	V <sub>GS</sub> =20V	
I <sub>GSS</sub>	Gate-to-source reverse leakage current	_	_	-400	- nA	V <sub>GS</sub> =-20V	
C <sub>ISS</sub>	Input capacitance	_	4670	_		V <sub>GS</sub> =0V, V <sub>DS</sub> =400V, <i>f</i> =1MHz	
Coss	Output capacitance	_	312	_	pF		
C <sub>RSS</sub>	Reverse transfer capacitance	_	8	_			
$C_{\text{O(er)}}$	Output capacitance, energy related <sup>b</sup>	_	497	_	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V to 400V	
C <sub>O(tr)</sub>	Output capacitance, time related c	_	1020	_	рі		
Q <sub>G</sub>	Total gate charge	_	68	100		V <sub>DS</sub> =400V, V <sub>GS</sub> =0V to 10V, I <sub>D</sub> =60A	
Q <sub>GS</sub>	Gate-source charge	_	30	_	nC		
$Q_{\text{GD}}$	Gate-drain charge	_	18	_			
Qoss	Output charge	_	430	_	nC	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V to 400V	
t <sub>D(on)</sub>	Turn-on delay	_	78	_		$V_{DS}$ =400V, $V_{GS}$ =0V to 12V, $R_{G}$ =15 $\Omega$ , $Z_{FB}$ =120 $\Omega$ at 100MHz,	
<b>t</b> <sub>R</sub>	Rise time	_	20	_	ns		
$t_{\text{D(off)}}$	Turn-off delay	_	132	_	] 113	I <sub>D</sub> =60A	
t <sub>F</sub>	Fall time	_	10	_			

#### Notes:

a. Dynamic on-resistance; see Figures 19 and 20 for test circuit and conditions

b. Equivalent capacitance to give same stored energy as  $V_{\text{DS}}$  rises from 0V to 400V

c. Equivalent capacitance to give same charging time as  $V_{DS}$  rises from OV to 400V

### **Electrical Parameters** (T<sub>J</sub>=25 °C unless otherwise stated)

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions	
Reverse Dev	Reverse Device Characteristics						
Is	Reverse current	_	_	60	А	V <sub>GS</sub> =0V, T <sub>C</sub> =100°C ≤15% duty cycle	
V	Doverso veltore 3	_	1.5	_	V	V <sub>GS</sub> =0V, I <sub>S</sub> =60A	
$V_{SD}$	Reverse voltage <sup>a</sup>	_	1.1	_		V <sub>GS</sub> =0V, I <sub>S</sub> =30A	
t <sub>RR</sub>	Reverse recovery time	_	100	_	ns	I <sub>S</sub> =60A, V <sub>DD</sub> =400V,	
Q <sub>RR</sub>	Reverse recovery charge	_	430	_	nC	di/dt=1000A/ms	
(di/dt) <sub>RM</sub>	Reverse diode di/dt <sup>b</sup>	_	_	3500	A/µs	Circuit implementation and parameters on page 3	

#### Notes:

a. Includes dynamic  $R_{DS(on)}$  effect

b. Reverse conduction di/dt will not exceed this max value with recommended R<sub>G</sub>.

### **Design Considerations**

The fast switching of GaN devices reduces current-voltage crossover losses and enables high frequency operation while simultaneously achieving high efficiency. However, taking full advantage of the fast switching characteristics of GaN switches requires adherence to specific PCB layout guidelines and probing techniques.

Before evaluating Transphorm GaN devices, see application note <u>Printed Circuit Board Layout and Probing for GaN Power Switches</u>. The table below provides some practical rules that should be followed during the evaluation.

#### When Evaluating Transphorm GaN Devices:

DO	DO NOT
Minimize circuit inductance by keeping traces short, both in the drive and power loop	Twist the pins of TO-220 or TO-247 to accommodate GDS board layout
Minimize lead length of TO-220 and TO-247 package when mounting to the PCB	Use long traces in drive circuit, long lead length of the devices
Use shortest sense loop for probing; attach the probe and its ground connection directly to the test points	Use differential mode probe or probe ground clip with long wire
See ANOOO3: Printed Circuit Board Layout and Probing	

#### **GaN Design Resources**

The complete technical library of GaN design tools can be found at transphormusa.com/design:

- Evaluation kits
- Application notes
- · Design guides
- · Simulation models
- Technical papers and presentations

#### Mechanical

#### 3 Lead TO-247 Package

